



Material Content Data Sheet



Sales Product Name		BCR 183 E6327		Issued		29. August 2013			
MA#		MA000446326							
Package		PG-SOT23-3-11		Weight*		8.80 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	noble metal	gold	7440-57-5	0.005	0.06		569		
	inorganic material	silicon	7440-21-3	0.043	0.49	0.55	4868	5437	
leadframe	non noble metal	chromium	7440-47-3	0.008	0.09		925		
	inorganic material	silicon	7440-21-3	0.001	0.01		62		
	non noble metal	titanium	7440-32-6	0.003	0.03		309		
wire	non noble metal	copper	7440-50-8	2.704	30.72	30.85	307201	308497	
	noble metal	gold	7440-57-5	0.012	0.14	0.14	1410	1410	
	encapsulation	organic material	carbon black	1333-86-4	0.058	0.66		6565	
		plastics	brominated resin	-	0.087	0.98		9848	
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.116	1.31		13130		
	plastics	epoxy resin	-	1.243	14.12		141151		
	inorganic material	silicondioxide	60676-86-0	4.277	48.58	65.65	485822	656516	
leadfinish	non noble metal	tin	7440-31-5	0.150	1.70	1.70	16999	16999	
plating	noble metal	silver	7440-22-4	0.098	1.11	1.11	11141	11141	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

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